

Fast & Flexible Mounter

DECAN S1

Designed and built with a focus over the 3 core values on chip mounter (actual productivity, placement quality, minimizing loss), this machine will provide you with the most optimized solution for high-mix production.



Model Name		DECAN S1	
Alignment		Fly Camera + Fix Camera	
The Number of Spindles		10 Spindle x 1 Gantry	
Placement Speed		47,000 CPH (Optimum)	
Placement Accuracy	Chip	± 28 μm @ Cpk ≥ 1.0	
	QFP	± 30 μm @ Cpk ≥ 1.0	
Component Range	Fly Camera	03015 ~ □16 mm	
	Fix Camera	~ □42 mm (Standard) □42 mm ~ □55 mm (MFOV) L55 mm ~ L75 mm Connector (MFOV)	
		Max. Height	10 mm (Fly), 15 mm (Fix)
PCB Size (mm)	Min.	L50 x W40*	
	Max.	Standard	~ L510 x W510*
		Option	~ Max. L1,500 x W460, L1,500 x W510*
PCB Thickness (mm)		0.38 ~ 4.2	
Feeder Capacity (8 mm Standard)	Standard	60 ea / 56 ea (Fixed Feederbase / Docking Cart)	
	Option	120 ea / 112 ea (Fixed Feederbase / Docking Cart)	
Utility	Power	3Phase, AC 200 / 208 / 220 / 240 / 380 / 415V	
		Max. 3.5 kVA	
Air Consumption	Air Consumption	5.0 ~ 7.0 kgf/cm ²	
		50 N ℓ / min (Vacuum Pump)	
Weight (H900 mm Standard)		Approx. 1,600 kg	
External Dimension (Standard)		L1,430 x D1,740 x H1,485 mm	

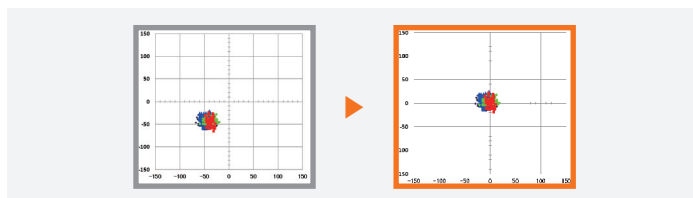
* If the PCB length is 1,500mm, the minimum size of the PCB should be 150mmx90mm.

※ The specification in this catalog is based on value measured at an optimized condition. The result may vary depending on the operating condition.

Stable Microchip Placement

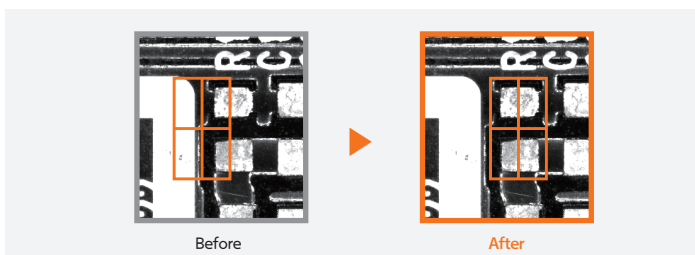
Run-Time Calibration

Maintains placement accuracy with the automatic calibration during production.



Automated Placement Point Teaching

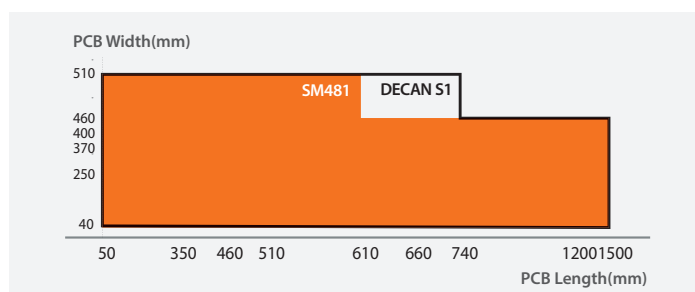
With the inspection and modification of placement points on standard chips, it significantly reduced the time required to check and fine-tune the placement coordinates during a model change.



The Best-in-Class Performance

Best in mid-class PCB applicability

- 510 x 510mm (standard) / 1500 x 460mm (option)
- Possible to produce PCBs up to 1,500mm(L) x 460mm(W)



Supports a fast NPI and sample production

- In the event of component recognition failure during initial product production, components are placed by editing / applying the component information and PCB coordinate without dumping them.
- Waste of components (zero) / Rapid model change / Allows mass production from the initial product.

Semi-Extend mode

- Maintains high productivity with Extended Mode during an array PCB production. Manages placement coordinates with Non-Extend Mode for easier teaching.